

bq27531EVM with bq27531 Battery Management Unit Impedance Track™ Fuel Gauge and bq24192 4.5-A, Switch-Mode Battery Charger for Single-Cell Applications

This evaluation module (EVM) is a complete evaluation system for the Battery Management Unit (BMU) chipset consisting of the bq27531-G1 fuel gauge and bq24192 battery charger. The EVM includes one bq27531 circuit, including a current sense resistor and one thermistor. In addition, the fuel gauge controls the bq24192 battery charger's settings and monitors its status via I²C communication lines. Together, the chipset provides all necessary components to monitor and predict capacity for a system-side fuel gauge solution as well as to charge the battery from either an adapter or USB input with up to 4.5-A of charge current. The circuit module connects directly across the battery pack. With the EV2300 interface board and software, the user can read the bq27531-G1 data registers, program the chipset for different pack configurations, log cycling data for further evaluation, and evaluate the overall functionality of the battery management unit solution under different charge and discharge conditions. The latest Windows™-based PC software can be downloaded from the product folder on the Texas Instruments Web site.

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Features

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1 Features

- Complete evaluation system for the Battery Management Unit chipset consisting of the bq27531-G1 Impedance Track fuel gauge and bq24192 4.5-A Battery Charger.
- · Populated circuit module for quick setup
- Personal computer (PC) software and interface board (orderable on TI website) for easy evaluation
- Software that allows data logging for system analysis (available in product folder on TI website)
- Ability to upgrade to the latest firmware version by flash reprogramming

1.1 Kit Contents

- bq27531-G1 and bq24192 chipset circuit module (PWR216)
- NTC103AT thermistor

This EVM is used for the evaluation of the bq27531-G1 and bq24192 BMU chipset. Ensure that you visit the product Web folder at <u>www.ti.com</u> to download the latest firmware version, evaluation software, and documentation for the associated product to be evaluated.

1.2 Ordering Information

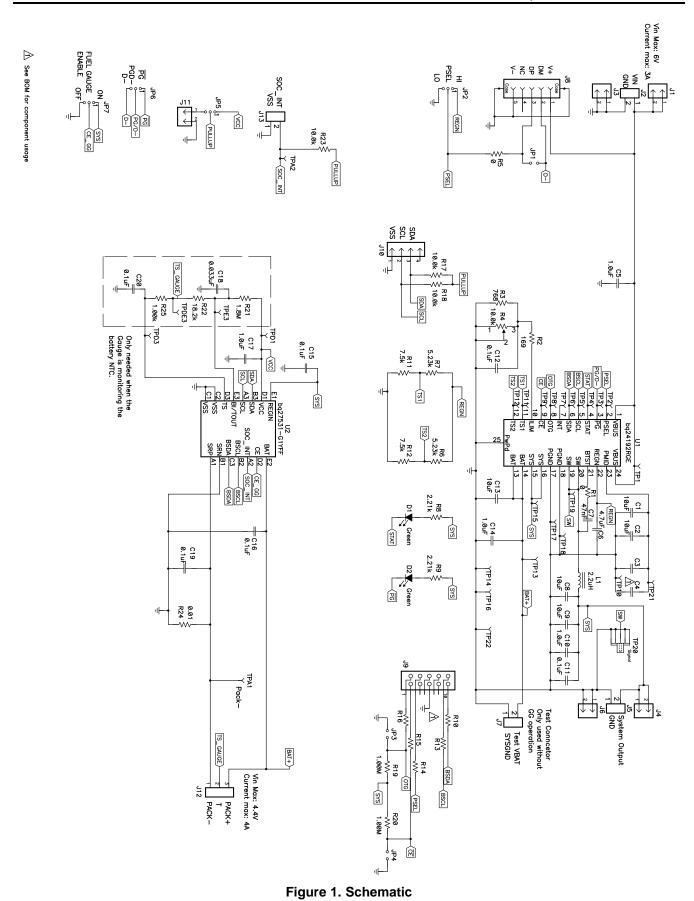
Table 1. Ordering Information

EVM PART NUMBER	CHEMISTRY	CONFIGURATION	CAPACITY	
bq27531EVM	Li-ion	1 cell	Any	

2 bq27531-Based Circuit Module

The bq27531-based circuit module is a complete and compact example solution of a bq27531 circuit for battery management. The circuit module incorporates a bq27531 battery gas gauge integrated circuit (IC) and all other components necessary to accurately predict the capacity of 1-series Li-ion cell.





bq27531EVM with bq27531 Battery Management Unit Impedance Track™ Fuel Gauge and bq24192 4.5-A, Switch-Mode Battery Charger for Single-Cell Copyright © 2013, Texas Instruments Incorporated Applications



bq27531-Based Circuit Module

2.1 Circuit Module Connections

Contacts on the circuit module provide the following connections:

- Direct connection to the battery pack (J12): PACK+, PACK-, and TS
- To the serial communications port (J10): SDA, SCL, and VSS
- Connection to system load (J5)
- Connection to charger (J2)
- Access to signal output (J13): SOC_INT

2.2 I/O Description

Header/Terminal Block	Description
J1–VIN	Adapter positive terminal
J2–VIN	Adapter positive terminal
J2–GND	Adapter negative terminal
J3-GND	Adapter negative terminal
J4-SYS	System positive terminal
J5-SYS	System positive terminal
J5-GND	System negative terminal
J6-GND	System negative terminal
J7-TEST	Test terminal
J8	USB Miniconnector
J9	USBTOGPIO 10-pin connector (not installed)
J10	EV2300 connector for using bq27531 software to communicate with bq27531 IC
J11	Allows SOC_INT to be tied to external pullup rather than VCC
J12-PACK+	Battery positive terminal
J12-T	Pack thermistor input that leads to IC TS pin
J12-PACK-	Battery negative terminal
J12-SOC_INT	SOC_INT output from gauge

2.3 Test Points

Test Point	Description
TP1	bq24192 IN voltage
TP2	bq24192 PSEL pin
TP3	bq24192 PG/D- pin
TP4	bq24192 STAT pin
TP5	bq24192 SCL = bq27531 BSCL - I2C communication clock line
TP6	bq24192 SDA = bq27531 BSDA - I2C communication data line
TP7	bq24192 INT pin
TP8	bq24192 OTG pin
TP9	bq24192 CE pin
TP10	PGND
TP11	bq24192 TS1 pin
TP12	bq24192 TS2 pin
TP13	bq24192 BAT pin
TP14	PGND
TP15	bq24192 SYS pin
TP16	PGND
TP17	PGND

4 bq27531EVM with bq27531 Battery Management Unit Impedance Track[™] Fuel Gauge and bq24192 4.5-A, Switch-Mode Battery Charger for Single-Cell Applications Copyright © 2013, Texas Instruments Incorporated

Circuit Module Physical Layouts, Bill of Materials, and Schematic

Test Point	Description
TP18	PGND
TP19	bq24192 SW pin
TP20	bq24192 SW signal
TP21	bq24192 PMID pin
TP22	PGND
TPA1	PACK-
TPA2	bq27531 SOC_INT pin
TPD1	bq27531 VCC pin
TPD3	bq27531 TS pin
TDPE3	External thermistor output
TPE3	bq27531 BI/TOUT pin

2.4 Control and Key Parameters Setting

Jumper	Description	Default Factory Setting
JP1 USB D+/D-	Shorting jumper for USB data lines DM (D-) and DP (D+). When shorted, USB input current limit defaults to 1.5 A. Otherwise, USB100 mode is selected.	INSTALLED
JP2 PSEL	 2-3 (PSEL = LO): Indicates that an ac adapter is connected to the USB input and sets the USB input current limit to 1.5 A. 1-2 (PSEL = HI): Indicates that a USB source is connected to the USB input and sets the input current limit to 500 mA. (DEFAULT) 	1-2 (PSEL = HI)
JP3 OTG	When installed, OTG feature will be disabled.	NOT INSTALLED
JP4 CHARGE ENABLE	When installed, charging is enabled.	INSTALLED
JP5 SOC_INT	2-3: SOC_INT is tied to external pull-up 1-2: SOC_INT is tied to onboard VCC through pull-up (DEFAULT)	1-2 VCC
JP6 D-/PG	2-3: Connect D-/PG to D- 1-2: Connect D-/PG to PG (DEFAULT)	1-2 PG
JP7 FUEL GAUGE ENABLE	1-2 ON: Fuel gauge enable (CE) pin high for normal operation (DEFAULT) 2-3 OFF: Fuel gauge enable (CE) pin low to disable gauging	1-2 ON

3 Circuit Module Physical Layouts, Bill of Materials, and Schematic

This section contains the board layout, bill of materials, assembly drawings, and schematic for the bq27531 circuit module.

3.1 Board Layout

This section shows the printed-circuit board (PCB) layers (Figure 2 through Figure 5), assembly drawing, and schematic for the bq27531 module.



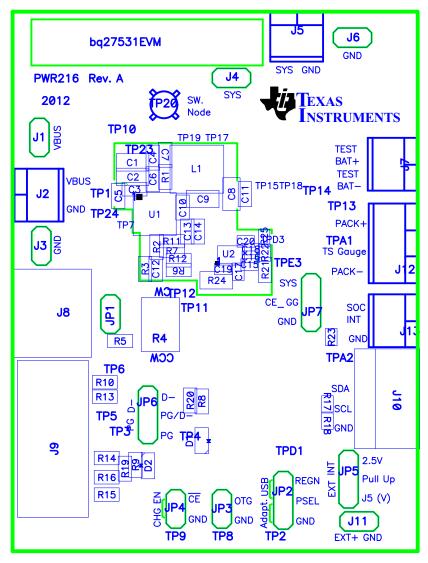


Figure 2. bq27531EVM-001 Layout – Silk Screen

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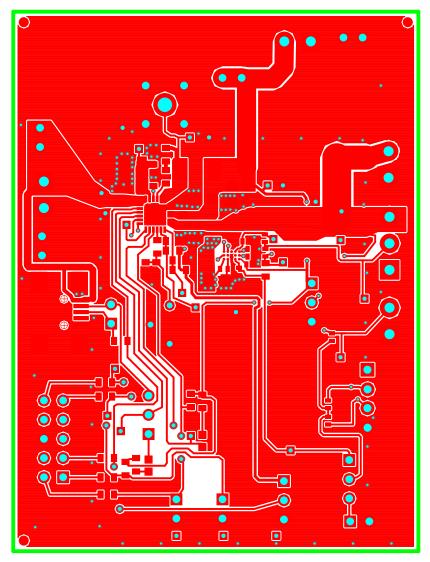


Figure 3. Layer 1



Circuit Module Physical Layouts, Bill of Materials, and Schematic

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Figure 4. Layer 2

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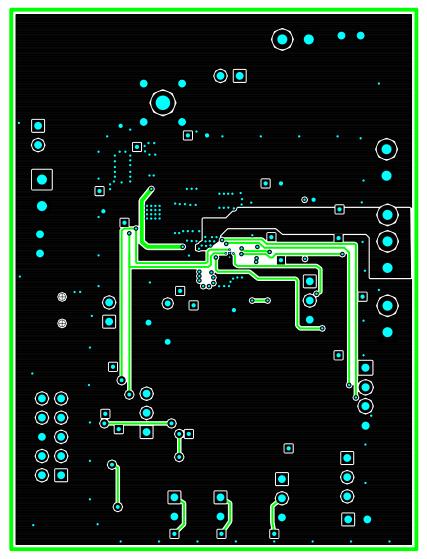


Figure 5. Layer 3



Circuit Module Physical Layouts, Bill of Materials, and Schematic

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Figure 6. Layer 4



Circuit Module Physical Layouts, Bill of Materials, and Schematic

3.2 Bill of Materials and Schematic

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C18	0.033uF	Capacitor, Ceramic, 16V, X7R, 10%	402	C1005X7R1C333K	TDK
4	C15, C16, C19, C20	0.1uF	Capacitor, Ceramic, 6.3V, X5R, 10%	402	C1005X5R0J104K050BA	TDK
1	C17	1.0uF	Capacitor, Ceramic, 6.3V, X5R, 10%	402	C1005X5R0J105K050BB	TDK
2	C11, C12	0.1uF	Capacitor, Ceramic, 25V, X5R, 10%	603	C1608X5R1E104K	TDK
2	C10, C14	1.0uF	Capacitor, Ceramic, 10V, X5R, 10%	603	C1608X5R1A105K080AC	TDK
1	C5	1.0uF	Capacitor, Ceramic, 25V, X5R, 10%	603	C1608X5R1E105K080AC	TDK
1	C6	4.7uF	Capacitor, Ceramic, 10V, X5R, 10%	603	CGB3B1X5R1A475K055AC	TDK
1	C13	10uF	Capacitor, Ceramic, 10V, X5R, 10%	603	C1608X5R1A106K080AC	TDK
1	C7	47nF	Capacitor, Ceramic, 10V, X5R, 10%	603	06033D473KAT2A	AVX
0	C3, C4	DNP	Capacitor, Ceramic, 10V, X5R, 10%	603		
4	C1, C2, C8, C9	10uF	Capacitor, Ceramic, 25V, X5R, 10%	805	C2012X5R1E106K125AB	TDK
0	J9	DNP	Connector, Male Straight 2x5 pin, 100mil spacing, 4 Wall	0.338 x 0.788 inch	N2510-6002-RB	3M
1	J8	UX60-MB-5ST	Connector, Recpt, USB-B, Mini, 5-pins, SMT	0.354 X 0.303 Inches	UX60-MB-5ST	Hirose Electric Co
2	D1, D2	Green	Diode, LED, Green, 2.1-V, 10-mA, 6-mcd	603	LTST-C190GKT	Liteon
5	J1, J3, J4, J6, J11	PEC02SAAN	Header, Male 2-pin, 100mil spacing	0.100 inch x 2	PEC02SAAN	Sullins
1	J10	22-05-3041	Header, Friction Lock Ass'y, 4-pin Right Angle	0.400 x 0.500	22-05-3041	Molex
1	L1	2.2uH	Inductor, SMT, 4.2A, 50.1milliohm	0.204 x 0.216 inch	IHLP2020BZER2R2M01	Vishay
3	JP1, JP3, JP4	PEC02SAAN	Header, Male 2-pin, 100mil spacing	0.100 inch x 2	PEC02SAAN	Sullins
4	JP2, JP5, JP6, JP7	PEC03SAAN	Header, Male 3-pin, 100mil spacing	0.100 inch x 3	PEC03SAAN	Sullins
1	R4	10.0k	Potentiometer, 3/8 Cermet, Single-Turn	0.25x0.17 inch	3266W-1-103LF	Bourns
1	R25	1.00k	Resistor, Chip, 1/16W, 1%	402	CRCW04021K00FKED	Vishay
3	R17, R18, R23	10.0k	Resistor, Chip, 1/16W, 1%	402	CRCW040210K0FKED	Vishay
1	R22	18.2k	Resistor, Chip, 1/16W, 1%	402	CRCW040218K2FKED	Vishay
2	R1, R5	0	Resistor, Chip, 1/10W	603	CRCW06030000Z0EA	Vishay
2	R6, R7	5.23k	Resistor, Chip, 1/10W, 1%	603	CRCW06035K23FKEA	Vishay
2	R19, R20	1.00M	Resistor, Chip, 1/10W, 1%	603	ERJ-3EKF1004V	Panasonic
2	R11, R12	7.5k	Resistor, Chip, 1/10W, 1%	603	CRCW06037K50FKEA	Vishay
1	R2	169	Resistor, Chip, 1/10W, 1%	603	ERJ-3EKF1690V	Panasonic
0	R10, R13, R14, R15, R16	DNP	Resistor, Chip, 1/10W, 1%	603		
1	R3	768	Resistor, Chip, 1/10W, 1%	603	ERJ-3EKF7680V	Panasonic



Table 2. Bill of Materials (continued)

1	R21	1.8M	Resistor, Chip, 1/10W, 1%	603	ERJ-3EKF1804V	Panasonic
2	R8, R9	2.21k	Resistor, Chip, 1/10W, 1%	603	ERJ-3EKF2211V	Panasonic
1	R24	0.01	Resistor, Chip, 1/4W, 1%	805	WSL0805R0100FEA18	Vishay
4	J2, J5, J7, J13	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED555/2DS	OST
1	J12	ED555/3DS	Terminal Block, 3-pin, 6-A, 3.5mm	0.41 x 0.25 inch	ED555/3DS	OST
0	TP1, TP2, TP3, TP4, TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12, TP13, TP14, TP15, TP16, TP17, TP18, TP19, TP20, TP21, TP22, TPA1, TPA2, TPD1, TPD3, TPDE3, TPE3	DNP	Test Point, 0.020 Hole	0.100 x 0.100 inch		
1	TP20	131-4244-00	Adaptor, 3.5-mm probe clip (or 131-5031- 00)	0.200 inch	131-4244-00	Tektronix
1	U1	bq24192RGET	IC, I2C Controlled 4.5A Single Cell USB/Adapter Charger	QFN-24	bq24192RGET	ТІ
1	U2	bq27531- G1YZFT	IC, Battery Management Unit Impedance Track Fuel Gauge With bq24192 Charger Controller	BGA	bq27531-G1YZFT	TI
1	RT1	10K	Thermistor, NTC, 3-A	0.095 X 0.150 inch	103AT-2	Semitec
5			Shunt, 100-mil, Black	0.100	929950-00	3M
1			РСВ		PWR216	Any



3.3 bq27531 Circuit Module Performance Specification Summary

This section summarizes the performance specifications of the bq27531 circuit module.

3.4 Recommended Operating Conditions

		Min	Тур	Max	Unit
Supply voltage, V _{IN}	Input voltage from ac adapter	4.2		6	V
System voltage, V_{SYS}	Voltage output at SYS terminal (depends on VBAT voltage and status of $V_{\rm INDPM}$ and input current limit circuits)	3.3		VBATR EG+4.17 %	V
Battery voltage, V_{BAT}	Voltage output at VBAT terminal (registers set via bq27531 software)	3	4.2	4.44	V
Supply current, I _{IN(MAX)}	Maximum input current from ac adapter input (registers set via bq27531 software)	1.5		3	A
Fast charge current, I _{CHRG(MAX)}	Battery charge current (registers set via bq27531 software)	0.550		3	A
Dperating junction temperature range, T _J		-40		125	°C

4 EVM Hardware and Software Setup

This section describes how to connect the different components of the EVM how to install the bq27531EVM PC software and.

4.1 Recommended Test Equipment

4.1.1 **Power Supplies**

- 1. Power Supply #1 (PS #1) capable of supplying 6 V at 3 A is required.
- 2. If not using a battery as the load, then power supply #2 (PS #2) capable of supplying up to 5 V at 5 A is required to power the circuit shown in Figure 7.

4.1.2 Load #1 Between BAT and GND

Testing with an actual battery is the best way to verify operation in the system. If a battery is not available, then a circuit similar to the one shown in Figure 7 can simulate a battery when connected to a power supply.

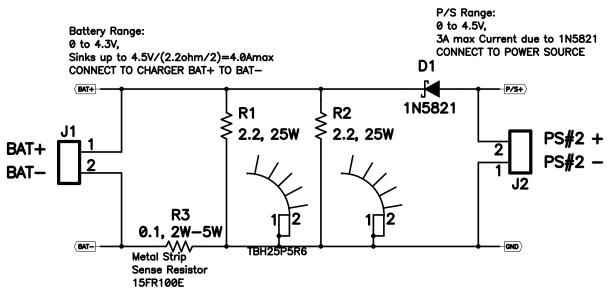


Figure 7. BAT_Load (PR1010) Schematic

4.1.3 Load #2 Between SYS and GND

Although not required, a resistive load capable of sinking up to 3 A can be used.

4.1.4 Meters

Three equivalent voltage meters (VM #) and two equivalent current meters (CM #) are required. The current meters must be able to measure 3-A current.

4.1.5 Test Equipment Setup

- 1. For all power connections, use short, twisted-pair wires of appropriate gauge wire for the amount of the current.
- 2. Set Power Supply #1 (PS #1) for 6-V, 3-A current limit and then turn off supply.
- 3. If BAT_Load as shown in Figure 8 is used, connect Power Supply #2 (PS #2) set to approximately 3.6 V to the input side (PS #2+/-) of BAT_Load, then turn off PS #2.
- 4. Connect the output side of the battery or BAT_Load in series with current meter to J12 (PACK+, PACK-). Ensure that a voltage meter is connected across J12 (PACK+,PACK-).
- 5. Connect VM #3 across J5 (SYS, GND).
- 6. Ensure jumpers are at the default factory settings per Section 2.4
- 7. Connect I2C port of EV2300 with J10 board using the assembled 4 colored-wire connector included with EV2300 kit (GND / BLACK at the bottom).
- 8. After the preceding steps have been performed, the test setup for PWR216 is configured as is shown in Figure 8



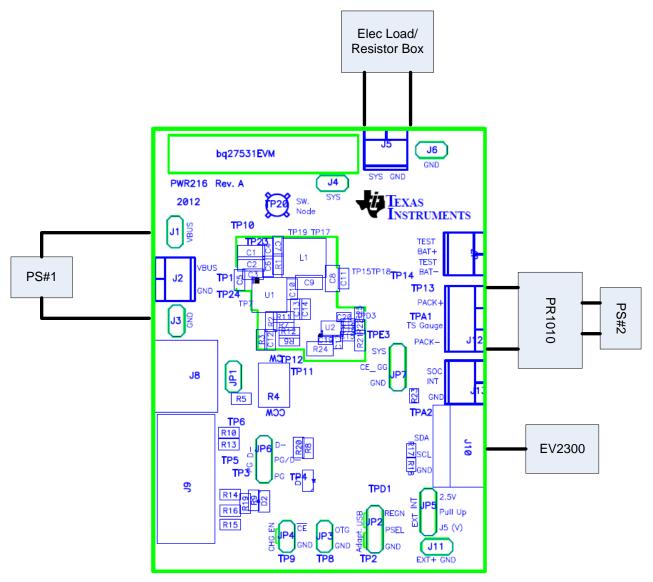


Figure 8. Test Setup for bq27531EVM (PWR216)

9. Turn on the computer. Open the bq27531 evaluation software. The main window of the software is shown in Figure 9 (DataRAM Screen).

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4.2 Software System Requirements

The bq27531EVSW software requires 32-bit versions of Windows 2000 or Windows XP. Drivers for Windows 98SE are provided, but Microsoft[™] no longer supports Windows 98; therefore, Windows 98 can have issues with USB driver support. The EV2300 USB drivers have been tested for Windows 98SE, but no assurance is made for problem-free operation with specific system configurations.

4.3 Software Installation

Find the latest software version in the bq27531 tool folder on <u>power.ti.com</u>. Make a search by part number for bq27531 to access the tool folder.

4.3.1 Using EV2300

Use the following steps to install the bq27531EVSW software when using EV2300:

- 1. Ensure that the EV2300 is not connected to the PC through a USB cable before starting this procedure.
- 2. Browse for the supported software link within the bq27531 TI web site product folder to find the downloadable evaluation software (EVSW) installation files.
- 3. Open the software file that was downloaded from the TI web site.
- 4. Follow the instructions on screen until the software installation is completed.
- 5. Before starting the EVSW, connect the EV2300 to the computer using the USB cable.
- 6. Wait until the system prompt "new hardware found" appears. Choose "select location manually", and use the "browse" button to point to subdirectory TIUSBWin2K-XP-1.
- 7. Answer "continue" to the warning that drivers are not certified with Microsoft[™].
- 8. After installation finishes, another system prompt "new hardware found" appears. Repeat steps 6 and 7, but specify the directory as TIUSBWin2K-XP-2.
- 9. Answer "continue" to the warning that drivers are not certified with Microsoft. Driver installation is now finished.

4.3.2 Using EV2400:

- 1. Ensure that the EV2400 is not connected to the PC through a USB cable before starting this procedure.
- 2. Browse for the supported software link within the bq27531 TI web site product folder to find the downloadable EVSW installation files.
- 3. Open the software file that was downloaded from the TI web site.
- 4. Follow the instructions on screen until the software installation is completed.

5 Troubleshooting Unexpected Dialog Boxes

The user that is downloading the files must be logged in as the administrator.

The driver is not signed, so the administrator must allow installation of unsigned drivers in the operating system policy.



6 Operation

This section details the operation of the bq27531 EVSW software.

6.1 Starting the Program

Run bq27531 EVSW from the Start | Programs | Texas Instruments | bq Evaluation Software menu sequence. The DataRAM screen (Figure 9) appears. Data begins to appear once the <Refresh> (single time scan) button is clicked, or when the <Keep Scanning> check box is checked. To disable the scan feature, deselect <Keep Scanning>.

The continuous scanning period can be set with the | Options | and | Set Scan Interval | menu selections. The range for this interval is 0 ms to 65,535 ms. Only items that are selected for scanning are scanned within this period.

The bq27531 EVSW provides a logging function which logs the values that were last scanned by EVSW. To enable this function, select the *Start Logging* button; this causes the *Keep Scanning* button to be selected. When logging is *Stopped*, the Keep Scanning button is still selected and has to be manually unchecked.

The logging intervals are specified under the | Options | menu with the maximum value of 65,535 ms. The *Log* interval cannot be smaller than the scan interval because this results in the same value being logged at least twice.

2	TEXAS INSTRUME	NTS			RΕ	AL WORLD S	IGN	ΑL	P	RO	CESSING				
	Refresh Logging Logg		Keep anning			<u>@</u> raphs									
	Name	Value	Unit	Log	Scan	Name	Value	Unit	Log	Scan	Name	Value	Unit	Log	Sco
	Control	0294	hex			Cycle Count	0	num	9		Level Taper Current	0	mA	M	V
_	Control Status	0294	hex	V		State of Charge	93	%	V		Calc. Charger Current	0	mA		V
	At Rate	0	mA			Instantaneous Current	1	mA	V	1	Calc. Charger Voltage	0	mΥ		V
	At Rate Time To Empty	65535	min	~		Internal Temp	21.65	degC	V	V	Prog. Charger Current	0	mA	V	V
d.	Temperature	22.75	degC	V		Remaining Capacity Unfilte	2158	mAH	₹	V	Prog. Charger Voltage	0	mΥ		V
1	Voltage	4093	mV	₹.	V	Remaining Capacity Filtere	2158	mAH	1		Charger Status	80	hex		V
1	Flags	0138	hex	V		Full Charge Capacity Unfilt	2338	mAH	V	V	Chrgr_InCtrl_Reg0	37	hex	$\overline{\mathbf{v}}$	V
L	Nominal Avail. Capacity	2195	mAH	V		Full Charge Capacity Filter	2338	mAH	R		Chrgr_POR_Config_Reg1	18	hex		V
	Full Available Capacity	2375	mAH	V		True State of Charge	93	%	V		Chrgr_Current_Reg2	60	hex	V	V
	Remaining Capacity	2158	mAH	V		Application Status	00	hex	₹	V	Chrgr_PreTerm_Reg3	11	hex		V
	Full Charge Capacity	2338	mAH	₹.		Res.Scale	0	dec	V		Chrgr_Voltage_Reg4	B2	hex	V	- Fe
	Average Current	0	mA	V		Qmax	2425	mAH	₹	1	Chrgr_TermTimer_Reg5	9A	hex	1	- Fe
	Time To Empty	65535	min	₹.		DODatEOC	144	dec	•		Chrgr_IRTherm_Reg6	03	hex		Ī
	Standby Current	-10	mA	V		DODO	1360	dec	V	1	Chrgr_OpCtrl_Reg7	4B	hex	V	V
	Average Power	0	mW	~		Passed Charge	0	mAH	₹	1	Chrgr_Status_Reg8	00	hex		Ī
	State of Health	96	%	₹.	R	QStart	180	mAH	-		Chror_Fault_Reg9	80	hex	V	F
	SOH Status	1	num	7	V	Charging Level	0	num	₹	1	Chror Revision RegA	2B	hex	$\overline{\mathbf{v}}$	F
	Flags / Status Bits Control Status - SCANN RSVD FAS INITCOMP HIBERNA Flags - SCANNING		SS XOZE		CSV SLEEP	CCA BCA O LDMD RUP_DIS	CVCMDCO VOK	WP (QEN						
	OT UT RSVD RSVD		I_GD		AIT_ID	DIV_CUR GG_CHORCTL BAT_DET SOCI	FC SYSDOW		CHG						
			_00	1 10	A11_10	BAI_DEI SUUL	57500W	<u> </u>	000						
	Application Status - SC/		Wb	1	RSVD	RSVD RSVD	RSVb		U PRI	OF 1					
	Charger Status - SCANN WAIT_CAD ERR	IING	VIED		VFAIL	AUTHFAEL INIT	RSVD		HIPMO						
	WATI COND CKK	1.00		w Fla		NOTEXAL INTE	K300	or			Show Static Data				

Figure 9. DataRAM Screen

This screen (Figure 9) shows the RAM data set. Additional Flag and Status data can be viewed at the bottom of the DataRAM screen.

Dragging the splitter bar (line that separates the Flags/Status data from Data Ram register values) changes the height of the Flags/Status Data display. Selecting | View |, then | Auto Arrange | returns the splitter bar to its original location.

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Operation

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6.2 Setting Programmable bq27531 Options

The bq27531 data flash comes configured per the default settings detailed in the bq27531 data sheet. Ensure that the settings are correctly changed to match the pack and application for the bq27531 solution being evaluated.

IMPORTANT: The correct setting of these options is essential to get the best performance.

The settings can be configured using the Data Flash screen (Figure 10).

TEXAS INSTRUMENT	rs	REA	L WORLD SI	GNAL	PRO	CESSING		
Bead All Wite All	Write A	all, <u>P</u> reserve	"Right click on constant name for more information					
Calibration	<u> </u>	Security) a	harger				
Configuration	ľ.	Gas Gauging	, ľ ocvi	l'ables	- <u>r</u> '	Default Ra Tables	Ra Tab	es
Name	Value	Unit	Name	Value	Unit	Name	Value	Uni
Safety			CC Threshold	2183	mAh	Integrity Data	-	
Over Temp	60.0	deqC	Design Capacity	2425	mAh	Full Reset Counter	0	nun
Under Temp	0.0	degC	SOH LoadI	-400	mA	Registers		
Temp Hys	3.0	degC	Default Temperature	25.0	deqC	Op Config	6167	flg
Charge Termination			Device Name	bq27531		SOC belta	1	%
Charging Voltage	4200	mV	Data Flash Version	0000	hex	12c Timeout	4	nue
Taper Current	121	mA	Discharge			DF Wr Ind Wait	0	uSe
Min Taper Capacity	25	mAh	SOC1 Set Threshold	150	mAh	OpConfig B	6F	flg
Taper Voltage	100	mV	SOCI Clear Threshold	175	mAh	OpConfig C	36	flg
Current Taper Window	40	Sec	SysDown Set Volt Threshok	3150	mΥ	Clk Ctl Reg	09	hex
FC Clear %	98	%	SysDown Set Volt Time	2	Sec	Power	-	
FC Clear Volt	0	mV	SysDown Clear Volt	3400	m٧	Flash Update OK Voltage	2800	mV
DODatEOC Delta T	5.0	degC	Final Voltage	3000	mΥ	Sleep Current	10	mA
Data			Def Avg I Last Run	-299	mA	Hibernate I	8	mA
Initial Standby	-10	mA	Def Avg P Last Run	-1131	mW	Hibernate V	2550	mV
-								

Figure 10. Data Flash Screen

To read all the data from the bq27531 data flash, click on menu option | Data Flash | Read All |.

To write to a data flash location, click on the desired location, enter the data and press <Enter>, which writes the entire tab of flash data, or select menu option | Data Flash | Write All |. The data flash must be read before any writes are performed to avoid any incorrect data being written to the device.

The | File | Special Export | menu options allows the data flash to be exported, but it configures the exported data flash to a learned state ready for mass production use.

The data-flash configuration can be saved to a file by selecting | File | Export | and entering a file name. A data-flash file also can be retrieved in this way, imported, and written to the bq27531 using the | Write All | button.

The module calibration data is also held in the bq27531 data flash.

The bq27531 allows for an automatic data-flash export function, similar to the DataRAM logging function. This feature, when selected via | Options | Auto Export |, exports Data Flash to a sequential series of files named as *FilenameNNNNN.gg* where N = a decimal number from 0 to 9.

The AutoExport interval is set under the | Options menu | with a minimum value of 15 s. The AutoExport filename also is set under the | Options menu |.



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When a check is next to | AutoExport |, the AutoExport is in progress. The same menu selection is used to turn on/off AutoExport.

If the Data Flash screen is blank, then the bq27531 that is being used may not be supported by the bqEVSW version that is being used. An upgrade may be required. Most of the Data Flash also cannot be read if the bq27531 is in Sealed mode.

7 Calibrate Screen

To ensure proper calibration, perform the following steps. These steps may or may not be required, depending on the type of calibration being performed. Only one calibration item can be selected and calibrated at a time.

7.1 To Calibrate the bq27531

Calibrate each item one at a time in the order presented in this document. Select the types of calibration to be performed by selecting the corresponding checkbox (see Figure 11).

Enter the measured values for the types selected, if necessary.

Then press the *Calibrate Part as indicated below* button. After all calibration is complete, close the Calibrate subwindow. While the Calibrate subwindow is open, even in the background, the calibration routines are running in firmware. Close the subwindow to ensure that they are stopped before proceeding with configuration or testing.

7.2 CC Offset Calibration

This performs the internal calibration of the coulomb counter input offset. Press the *Calibrate Coulomb Counter* button.

7.3 Voltage Calibration

- Measure the voltage across Pack+ and Pack- with a calibrated meter.
- Type the voltage value in mV into Enter Actual Voltage .
- Measure the temperature for PACK.
- Type the temperature value into Enter Actual Temperature.
- Press the Calibrate Voltage and Temperature as indicated below button.

7.4 Board Offset Calibration

This performs the offset calibration for the current offset of the board. It takes approximately 35 seconds to complete.

It is expected that no current is flowing through the sense resistor while performing this calibration step. Remove load and short PACK– to GND.

Press the Calibration Board Offset button.

7.5 Pack Current Calibration

- Connect a load to GND and SYS that draws approximately 1 A, or connect a current source to GND and Pack–. Ensure that the Measured Current reported is negative, or else reverse the connections.
- Measure the current with a calibrated meter, and type the value into Enter Actual Current using (-) for current in discharge direction.
- Press the Calibrate Pack Current button.



Calibrate Screen

		luation Software - bg27531G1 v1.02 - [Host Calibration]		
🏂 Eile Window H	<u>i</u> elp		- 6	8 ×
	TEXAS INSTRUMEN		Version: 1.3.0.7	
Plea	ase ensure that scanning/con	mmunication is off on all other open windows.		
-c	Coulomb Counter Offs	set Calibration-Step 1		
DataRAM	Calibrate Coulomb Counter	Ensure that no load current is flowing.		
	oltage and Tempera	ature Calibration-Step 2		
Data Flash	Calibrate Vokage and Temperature as indicated below			
I2C Pro	Voltage □ Voltage Cal	Measured Enter actual voltage 4033 mV 4000 mV		
Calibrate	Temperature	Measured Enter actual temperature temperature		
	Temperature	22.6 °C 25 °C		
Version	Board Offset Calibrati	ion-Step 3		
Ĩ.	Calibrate Board Offset	Ensure that no load current is flawing. OC Offset is Updated with this command		
- P	ack Current Calibrat	tion-Stop 4		
0%. Fuel Gauge	Calibrate Pack. Current	Measured current Enter actual current Apply a discharge load. Discharge current is a negative value. Charge current is positive. A volage applied between Cell ground and Pack- will force current through sense resistor.		
93% Communication DK.		SBS Task Progress: 100	% Task Completed. 03:53:01	ID PH
communication UK.		505 Task Progress: 1004	s rask completed. U3:53:0	JO FM

Figure 11. Calibration Screen



8 I2C Pro Screen

8.1 *I*²C Communication

The read/write operations of the I2C Pro function is not specific to any gas gauge. These operations serve as general-purpose communication tools (Figure 12).

े Texas Instruments by Gas Gauge Evaluation Software - bg27531G1 v1.02 - [Pro screen: I2C over I2C lines]	
b Ele Window Help	- 8 ×
Caution: This screen is for advanced users. Some commands may cause permanent damage to hardware. All Values in hexadecimal(No 12C pa	
DataRAM Read I2C Data Block. I2C Command 40 Read Data	
Data Flash Write 12C Data Block 12C Command 00 Data Block 000f	
Calibrate Read/Write 12C Byte 12C Command 00Bead Byte Byte 00Write Byte]	
Vension Programming C\Documents and Settings\a00666575\Desktop\bq27531 Program Execute	
1007. Bead to '.senc Be 05. Fuel Gouge 93%	
Communication DK. SBS Task Progress: 100% Task Completed.	03:53:35 PM

Figure 12. I2C Pro Screen

9 Related Documentation From Texas Instruments

To obtain a copy of any of the following TI documents, call the Texas Instruments Literature Response Center at (800) 477-8924 or the Product Information Center (PIC) at (972) 644-5580. When ordering, identify this document by its title and literature number. Updated documents also can be obtained through the TI Web site at www.ti.com.

• bq27531, System-Side Impedance Track[™] Fuel Gauge With Integrated LDO data sheet (SLUSBE7)

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General Statement for EVMs including a radio

User Power/Frequency Use Obligations: This radio is intended for development/professional use only in legally allocated frequency and power limits. Any use of radio frequencies and/or power availability of this EVM and its development application(s) must comply with local laws governing radio spectrum allocation and power limits for this evaluation module. It is the user's sole responsibility to only operate this radio in legally acceptable frequency space and within legally mandated power limitations. Any exceptions to this are strictly prohibited and unauthorized by Texas Instruments unless user has obtained appropriate experimental/development licenses from local regulatory authorities, which is responsibility of user including its acceptable authorization.

For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant

Caution

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- · Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

For EVMs annotated as IC – INDUSTRY CANADA Compliant

This Class A or B digital apparatus complies with Canadian ICES-003.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Concerning EVMs including radio transmitters

This device complies with Industry Canada licence-exempt RSS standard(s). Operation is subject to the following two conditions: (1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concerning EVMs including detachable antennas

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication.

This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Cet appareil numérique de la classe A ou B est conforme à la norme NMB-003 du Canada.

Les changements ou les modifications pas expressément approuvés par la partie responsable de la conformité ont pu vider l'autorité de l'utilisateur pour actionner l'équipement.

Concernant les EVMs avec appareils radio

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes : (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante.

Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

[Important Notice for Users of this Product in Japan]

This development kit is NOT certified as Confirming to Technical Regulations of Radio Law of Japan

If you use this product in Japan, you are required by Radio Law of Japan to follow the instructions below with respect to this product:

- Use this product in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
- 2. Use this product only after you obtained the license of Test Radio Station as provided in Radio Law of Japan with respect to this product, or
- 3. Use of this product only after you obtained the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to this product. Also, please do not transfer this product, unless you give the same notice above to the transferee. Please note that if you could not follow the instructions above, you will be subject to penalties of Radio Law of Japan.

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